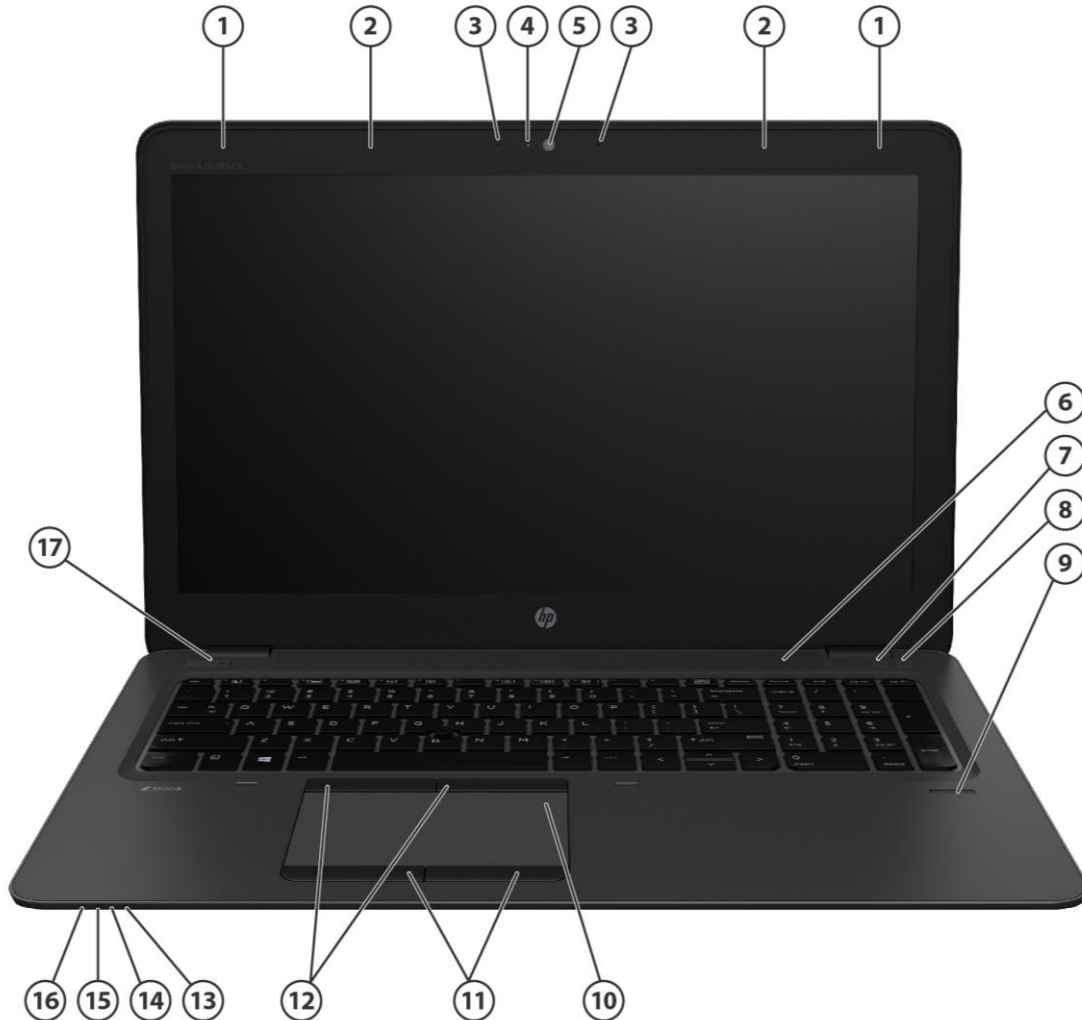


Overview

HP ZBook 15u G4 Mobile Workstation

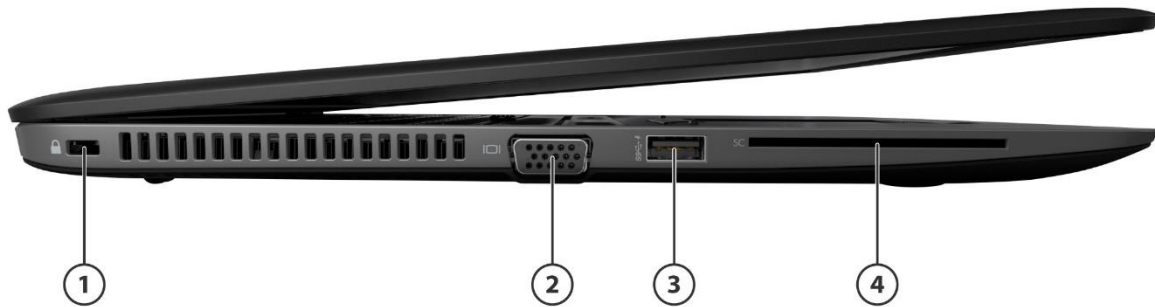


1. Wireless LAN antennas
2. WWAN antennas (selected products only)
3. Internal microphones (2)
4. Webcam light
5. Webcam
6. Speakers
7. Wireless On/Off button
8. Volume mute button
9. Fingerprint reader (select models only)

Front

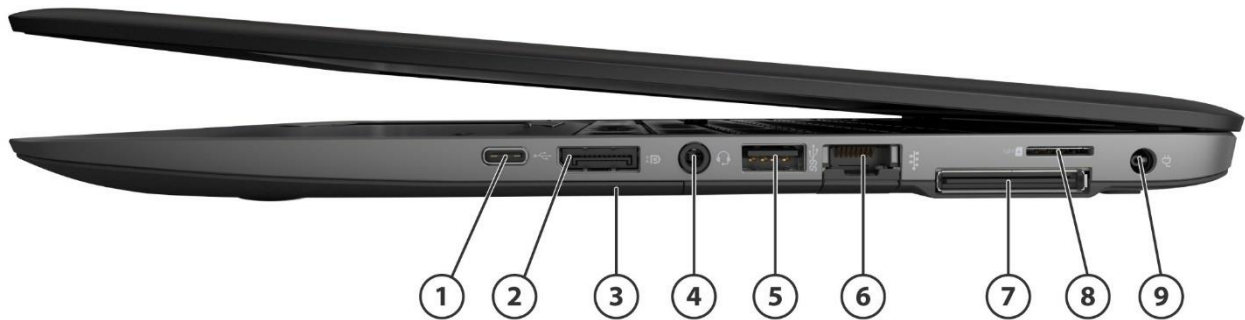
10. Touchpad
11. Lower Touchpad buttons (right and left click buttons)
12. Upper Touchpad buttons (right and left click buttons)
13. Storage light indicator
14. Battery light indicator
15. Power light indicator
16. Wireless light indicator
17. Power button

Overview



Left

- 1. Security lock slot
- 2. VGA port
- 3. USB 3.0 port (charging)
- 4. Smart Card reader



Right

- 1. USB 3.1 (Gen 1)
- 2. DisplayPort™
- 3. SD Card Reader
- 4. Headphone/Microphone Combo Jack
- 5. USB 3.0 port
- 6. RJ-45 / Ethernet
- 7. Side Docking connector
- 8. SIM Module Slot
- 9. Power connector

Overview

At A Glance

- Windows® 10 editions, or FreeDOS
- Value performance form factor and thinner industrial design than previous generation workstation grade products.
- Thin & light value performance industrial design, Casted magnesium-reinforced chassis, top cover frame features soft touch paint with lightweight aluminum insert anodized in HP's new "Space Silver" color with chemical etching. Backlight keyboard in full aluminum deck with magnesium bottom reinforcement, chemically strengthened glass touchpad, and updated system functions indicators. HP Spill Resistant Keyboard with Durakeys, touchpad buttons with Duracoat finish.
- Designed to pass military standard MIL-STD-810G testing*.
- Workstation-caliber AMD FirePro™ discrete graphics: AMD FirePro™ W4190M (2 GB dedicated GDDR5); AMD Enduro™ graphics technology.
- ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures
- Choice of 7th generation Intel® Core™ i7 and i5 processors
- Intel® Core™ i7 with vPro™ and Core™ i5 with vPro™ technology (optional)
- HP Performance Advisor for optimal configuration, compatibility and performance
- Up to two SODIMMs, for system memory up to 32GB
- Supports up to 3 independent displays via internal LCD Panel, system DisplayPort™, system VGA, or using the HP UltraSlim Docking Station DisplayPort™ and VGA ports (sold separately). Supports DisplayPort™ 1.2 monitors.
- Bang and Olufsen audio optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal clear dialog without distortion at high volume
- 3-cell (51 WHr) HP Long Life Battery
- 2 discrete buttons with LED indicator for convenient one touch access: Wireless On/Off, Volume Mute
- Widescreen 15-inch diagonal anti-glare LED-backlit display:
- FHD (1920x1080) standard viewing angle, FHD (1920x1080) ultrawide viewing angle, UHD (3840x2160) ultrawide viewing angle, or FHD Touch (1920x1080) standard viewing angle
- Supports wireless LAN and wireless WAN options for connectivity on the go.
- Two dedicated drive slots. (1) M.2 slots and (1) 2.5" drive bay. Both can be populated at the same time.
- Security features including HP Client Security Manager, with central management
- Low halogen, ENERGY STAR® certified and EPEAT® TBD registered in the U.S. EPEAT® status varies by country- please see epeat.net.
- HP BIOS self-healing technology including HP Sure Start to prevent, detect, and remedy known and unknown BIOS attacks.

* MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

Preinstalled OS Windows® 10 Pro 64*
Windows® 10 Home Single Language 64
FreeDOS 2.0

Supported OS Windows® 10 Enterprise 64*

* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Kaby Lake, Apollo Lake, Bristol Ridge and forward processors or provide any Windows® 8 or Windows 7 drivers on <http://www.support.hp.com>

PROCESSOR*

7th Generation Intel® Core™ i7 7600U (2.8 GHz, 4 MB cache, 2 cores) * Up to 3.9 GHz with Intel® Turbo Boost Technology

7th Generation Intel® Core™ i7 7500U (2.7 GHz, 4 MB cache, 2 cores) * Up to 3.5 GHz with Intel® Turbo Boost Technology

7th Generation Intel® Core™ i5 7300U (2.6 GHz, 3 MB cache, 2 cores) * Up to 3.5 GHz with Intel® Turbo Boost Technology

7th Generation Intel® Core™ i5 7200U (2.5 GHz, 3 MB cache, 2 cores) * Up to 3.1 GHz with Intel® Turbo Boost Technology

* Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of higher performance.

Also note that the Intel® Turbo Boost is based on max GHz for a single core.

Features

CHIPSET

Non-applicable, processor specific

INTEL® CORE™ I5 WITH VPRO/CORE™ I7 WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™ and Core™ i7 with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® Centrino® WLAN module and a preinstalled Windows operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update mobile workstations regardless of their power state.

* Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™ technology, such as Intel Active Management technology and Intel Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core™ i7 with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Intel® HD 620 Graphics*

AMD FirePro™ W4190M (2 GB dedicated GDDR5) **

Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.3capable

AMD Enduro™ Technology supported.

* HD content required to view HD images

** Supports up to 3 independent displays via internal LCD Panel, system DisplayPort™, system VGA, or using the HP UltraSlim Docking Station DisplayPort™ and VGA ports (sold separately).

DISPLAY

Internal

15.6" diagonal LED backlit FHD UWVA IPS eDP anti-glare + PSR (Panel Self Refresh) (1920 x 1080);

15.6" diagonal LED backlit FHD SVA eDP anti-glare (1920 x 1080);

15.6" diagonal LED UHD UWVA IPS anti-glare (3840 x 2160)

15.6" diagonal Touch LED-backlit FHD SVA (1920 x 1080)

External

Up to 30-bit (2³⁰) per pixel "Deep Color"

(total of 1,073,741,824 color variations)

VGA

Port supports resolutions up to 1920 x 1200 at 60 Hz, and lower resolutions up to 75 Hz.

Features

DisplayPort™ w/MST (Multi-stream Transport)

Supports resolutions up to UHD 3840 x 2160, 24/30-bit color depth at 60 Hz, and WUXGA (1920 x 1200) monitors, with 24/30-bit color depth up to 120 Hz.

DisplayPort™ Features

- Multi-stream Transport (MST): Multi-stream Transport is a DisplayPort™ 1.2 feature that allows daisy chaining of DisplayPort™ 1.2 monitors (requires monitor with DisplayPort™ 1.2 MST capability), or the use of DisplayPort™ 1.2 hubs with MST to achieve a maximum of 3 active displays.

DVI-D (single link)

DVI support requires a DP-to-DVI adapter (sold separately). Dual-Link DVI is supported with an active USB powered adapter (sold separately).

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Primary Storage Bay

SATA, 2.5" Hard Drive*

1 TB 5400 rpm Hard Drive
500 GB 7200 rpm Hard Drive
500 GB 7200 rpm Self Encrypting Drive (Opal2)
500 GB 7200 rpm Self Encrypting Drive FIPS 140-2 compliant
500 GB 5400 rpm Hybrid Drive (8 GB cache)

M.2 SATA SED SSD

256 GB SATA-3 Self-Encrypting (Opal 2) MLC Solid State Drive
512GB SATA-3 SS TLC SSD FIPS-140-2

HP Z Turbo Drive (NVMe PCIe SSD)

256GB PCIe (NVMe) TLC Solid State Drive
256GB PCIe (NVMe) MLC Solid State Drive
512GB PCIe (NVMe) MLC Solid State Drive
1TB PCIe (NVMe) MLC Solid State Drive
512GB PCIe (NVMe) TLC Opal 2 Solide State Drive

HP 3D DriveGuard (Windows only)

The hard drive is mounted directly to the notebook frame, reducing the transmission of shock to the hard drive.

NOTE: For Solid State Drives or Hard Drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (and 10) is reserved for system recovery software.

Features

DRIVE CONTROLLERS

2.5" Storage Bays and M.2 Storage Bay (SATA):	SATA-3 for HDD and SATA-3 for SSD
HP Z Turbo Drive:	PCIe NVMe SSD
RAID:	Not supported

NOTE: Raid 0, 1 supported only on SATA drives.

MEMORY

Standard

32 GB DDR4 1.2V Non ECC SDRAM (Transfer rates up to 2133MT/s)
Two SODIMM slots supporting dual-channel memory
4 GB, 8GB and 16 GB SODIMMs

Maximum

Upgradeable to 32768 MB with optional 16384 MB SODIMMs in 2 slots

Dual-channel

Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

* Maximum memory capacities assume Windows 64-bit operating systems or Linux. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Communications

Integrated Intel® I219-LM Gigabit* Network Connection (vPro configurations)
Intel® I219-V 10/100/1000 Ethernet (non-vPro configurations)

Wireless

Secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth is also available (factory configurable only) combined with the supported wireless LAN option.

802.11 Wireless LAN*

Intel® Dual Band Wireless-AC 8265 802.11 a/b/g/n/ac (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (vPro)
Intel® Dual Band Wireless-AC 8265 802.11 a/b/g/n/ac (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (non-vPro)
Intel® Dual Band Wireless-AC 3168 802.11 ac (1x1) WiFi and Bluetooth 4.2 Combo Adapter (non-vPro)

Wireless WAN - Mobile Broadband **

HP It4132 LTE/HSPA+ 4G Mobile Broadband Module
HP hs3210 HSPA+ Mobile Broadband Module

Features

HP It4120 Qualcomm® Snapdragon™ X5 LTE Mobile Broadband Module

Near Field Communications (NFC)

HP Module with NXP NFC Controller NPC100

* Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

** WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

AUDIO/MULTIMEDIA

Audio

Bang and Olufsen audio

Integrated stereo speakers

Integrated microphone (dual-microphone array when equipped with optional webcam)

Button for volume mute; function keys for volume up and down

Combo mic-in / stereo headphone-out jack

Webcam

720p HD webcam*

- HD format (widescreen)
- Supports videoconferencing and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing
- Improved low light sensitivity
- Improved dynamic range

* HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Optional backlit keyboard with Function key control to toggle backlit brightness setting - off/full/half brightness

The HP spill-resistant keyboard is designed using a thin layer of Mylar film under the keyboard and a drain system that funnels fluid through a hole in the bottom of the notebook. This minimizes the risk of damage to sensitive components underneath. The 100-key compatible keyboard features a full-pitch key layout with desktop keyboard features, such as editing keys, both left and right control and alt keys, function keys, and 18.0 x 18.4 mm key pitch (center-to-center spacing). U.S. and International key layouts are available. Other features include hot keys for instant access to power conservation and brightness.

Pointing Devices

Touchpad with On/Off button, two-way scroll, gestures, two pick buttons

Point stick with two additional point stick buttons

Image sensor touchpad for enhanced performance and improved precision on scroll and gesture

Buttons and Function Keys

Separate launch buttons provide easy access to the following features: wireless on/off, volume mute. Function keys provide

Features

control of the following features: standby mode, external display, volume down, volume up, HP Power Assistant (Windows® 7 only), and display brightness.

SOFTWARE AND SECURITY

Preinstalled Software with Windows Operating System

BIOS

HP BIOSphere¹
HP Sure Start Gen3
HP DriveLock¹² | HP Automatic DriveLock
BIOS Update via Network
Master Boot Record Security
Power On Authentication
Secure Erase²
Absolute Persistence Module³
Pre-boot Authentication

Communication

HP Mobile Connect Pro (Windows 8.1 and Windows 10 only)⁴
Native Miracast Support⁵
HP MAC Address Manager

HP Value Add Software

HP 3D DriveGuard
HP ePrint Driver + JetAdvantage⁶
HP Hotkey Support
HP Recovery Manager¹¹
HP Jumpstart
HP Support Assistant
HP Noise Cancellation Software
HP Performance Advisor
HP Remote Graphics Software
HP Velocity

Microsoft Products

Buy Office
Bing Search
Skype⁷

Manageability

HP Driver Packs¹¹
HP SoftPaq Download Manager (SDM)
HP System Software Manager (SSM)⁸
HP BIOS Config Utility (BCU)⁸
HP Client Catalog⁸
HP Manageability Integration Kit for Microsoft SCCM⁸
HP Image Assistant⁸
LANDESK Management⁹

For more information on HP Client Management Solutions refer to: <http://www.hp.com/go/clientmanagement>.

Client Security Software

- HP Client Security Suite Gen 3

Features

- HP Security Manager (including Credential Manager and Password Manager)
- HP Drive Lock
- HP Fingerprint Sensor
- HP Password Manager
- Absolute Persistence Module
- Power On Authentication
- Microsoft Defender¹³

Standard

Trusted Platform Module (TPM) 1.2 Embedded Security Chip (Common Criteria EAL4+ Certified). Field upgradeable to TPM 2.0¹⁰

HP Fingerprint Reader

For more information on HP Client Security Software Suite, refer to <http://www.hp.com/go/clientsecurity>.

1. Available only on business PCs with HP BIOS.
2. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
3. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: <http://www.absolute.com/company/legal/agreements/> computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
4. HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to <http://www.hp.com/go/mobileconnect>
5. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: <http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast>
6. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see <http://www.hp.com/go/eprintcenter>). Requires optional broadband module. Broadband use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
7. Skype is not offered in China.
8. Not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>
9. Subscription required.
10. This product ships with TPM 1.2 with option to upgrade to TPM 2.0. Upgrade utility is expected to be available by the end of 2015 via HP Customer Support
11. Models shipped with Windows 7 include HP Recovery Manager. HP Recovery Manager enables fast recovery of the factory preinstalled image if the system becomes corrupted or if important system files are accidentally deleted. Up to 36 GB (for Windows 7) of system and up to 36 GB (for Windows 10) disk is reserved for system recovery software
12. DriveLock feature only supported with SATA drives. DriveLock feature not supported on HP Z Turbo Drive PCIe SSDs.
13. Opt in and internet connection required for updates

Workstation ISV Certifications

Find the latest list of certifications at: <http://www.hp.com/go/isv>

HP Remote Graphics Software

The remote desktop solution for serious workstation users and their most demanding applications.

Download at: <http://www.hp.com/go/RGS>

HP Performance Advisor

Features

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements.

Download at: <http://www.hp.com/go/performanceadvisor>

Security

See Software section above.

Other Standard Security Features

Integrated Smart Card Reader

One-Step Logon

Security lock slot

Support for Intel® AT

Optional Security Features

HP Fingerprint Sensor (optional)

Absolute Data Protect* with GPS Tracking - Subscription based security solution providing the ability to track, initiate physical recovery, conduct asset management, and perform remote data delete by utilizing GPS technology. GPS functionality requires HP Mobile Broadband Module.

* The Absolute Data Protect agent is shipped turned off, and must be activated by customers when they purchase a subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S.

HP CENTRAL MANAGEMENT

HP offers a variety of scalable hardware, software, and BIOS-based security features to help you defend your organization against viruses and other threats. These integrated security features safeguard what matters to you the most - your data, device and identity. Now, be confident your fleet of devices is protected in multiple layers of HP Client Security protection.

HP BIOS Protection keeps you up and running with enhanced protection against virus attacks and other threats. And if the BIOS is accidentally compromised, the auto recovery feature automatically restores it to its fully functional state.

HP Sure Start detects and negates a BIOS attack with automatic recovery of the BIOS even when the installation is accidentally compromised (i.e. power outage). When HP Sure Start heals the BIOS an event log is generated that an IT administrator can retrieve so the business is aware of a BIOS attack. Golden copy of BIOS is stored in protected nonvolatile memory providing redundant, hardware-based protection against a new generation of attacks.

An optional fingerprint reader and integrated Smart Card Reader help keep your identity secure. The security cable slot helps keep your notebook physically secure.

You can even permanently destroy data on your hard drive in preparation for your system disposal or redeployment with Secure Erase.

Features

POWER

Power Supply

HP 65W Slim Smart AC Adapter

Primary Battery

HP 3-cell Long Life Polymer Battery (51 Whr)

Battery Life

Battery life up to 12 hours 14 minutes (with 51Whr battery, FHD panel, SATA SSD, AMD W4190M, Hybrid graphics)*

System Standby Time

Up to TBD weeks**

*Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark <https://bapco.com/products/mobilemark-2014/> for additional details.

** Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

AMD® Enduro™ Technology

Hibernation

Standby

ACPI compliance

ENVIRONMENTAL

US ENERGY STAR®

IT ECO declaration

EPEAT® registered where applicable. EPEAT® registration varies by country. See <http://www.epeat.net> for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.

NOTE: This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks.

WEIGHTS & DIMENSIONS

Weight

Starting at 4.18 lb. (1.9 kg)

Dimensions (w x d x h)

15.09 x 10.1 x 0.79 in

383.3 x 257.7 x 19.9 mm

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components. Weight includes 3 cell 46Whr battery, without hard drive and with 256 GB Z Turbo Drive (PCIe SSD).

Features

PORTS/SLOTS

Ports

Left side:

- (1) VGA
- (1) USB 3.0 Charging Port
- (1) Security lock slot

Right side:

- (1) USB 3.1 Gen 1
- (1) USB 3.0 Port
- (1) DisplayPort™ 1.2
- (1) Headphone/Microphone Combo
- (1) RJ-45 / Ethernet
- (1) Side Docking connector
- (1) Power connector

Digital Media Slots

- (1) SD UHS-II Flash Media slot – Supports next generation SD (Secure Digital), backward compatible to SDHC, SDXC
 - (1) Integrated Smart Card Reader (Compatible with ISO 7816 compliant Smart Cards PC/SC interface support)
-

SERVICE AND SUPPORT

Limited 3-year or 1-year limited warranty options available, depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Optional¹ HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at <http://www.hp.com/go/cpc>.

Sold separately or as an optional feature.

1. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.
-

Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5 V dc @ 3.3 A		
	Average Operating Power	AMD FirePro™ Graphics	Windows® 7 (32-bit) 16.28 W	Windows® 7 (64-bit) 16.8 W
Temperature	Max Operating Power	< 65 W		
	Operating	32° to 95° F (0° to 35° C) (not writing optical) 41° to 95° F (5° to 35° C) (writing optical)		
Relative Humidity	Non-operating	-4° to 140° F (-20° to 60° C)		
	Operating	10% to 90%, non-condensing		
Shock	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature		
	Operating	40 G, 2 ms, half-sine		
Random Vibration	Non-operating	200 G, 2 ms, half-sine		
	Operating	0.75 grms		
Altitude (unpressurized)	Non-operating	1.50 grms		
	Operating	-50 to 10,000 ft. (-15.24 to 3,048 m)		
Planned Industry Standard Certifications	Non-operating	-50 to 15,000 ft. (-15.24 to 12,192 m)		
	UL	Yes		
	CSA	Yes		
	FCC Compliance	Yes		
	ENERGY STAR®	Select models*		
	EPEAT®	Gold target**		
	ICES	Yes		
	Australia / NZ A-Tick Compliance	Yes		
	CCC	Yes		
	Japan VCCI Compliance	Yes		
	KCC	Yes		
BSMI	Yes			
CE Marking Compliance	Yes			
MIL STD***	Planned			

* Configurations of the HP ZBook 15u G4 that are ENERGY STAR® certified are identified as HP ZBook 15u G4 ENERGY STAR® on HP websites and on <http://www.energystar.gov>.

** EPEAT® registration varies by country. See <http://www.epeat.net> for registration status by country.

EPEAT status listed above applies to U.S.

*** MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

For accessibility information on HP products, please visit: <http://www.hp.com/accessibility>.

Technical Specifications – Displays

DISPLAYS

15.6" diagonal LED-backlit FHD UWVA IPS eDP anti-glare + Panel Self Refresh (PSR) (1920 x 1080)

Dimensions (W x H)	360 x 224.3 (mm) max
Active Area	344.2 x 193.5 (mm)
Weight	360g (max)
Surface Treatment	Anti-glare
Contrast Ratio	600:1 (typical)
Refresh Rate	60 Hz
Brightness	300 nit (typical)
Pixel Resolution	Format 1920 x 1080 (FHD)
	Configuration RGB Stripe
Backlight	LED
PPI	142
Viewing Angle	UWVA 85/85/85/85

15.6" diagonal LED backlight FHD eDP SVA Anti-glare (1920 x 1080)

Outline Dimensions (W x H x D)	360 x 224.3 (mm) max
Active Area	344.2 x 193.5 (mm)
Weight	360 g max.
Diagonal Size	15.6" (inch)
Surface Treatment	Anti-Glare (AG)
Contrast Ratio	400:1 (typical)
Refresh Rate	60Hz
Brightness	300nits
Pixel Resolution	Format 1920 x 1080 (FHD)
	Configuration RGB
Interface	eDP 1.2 (2 lane)
LCD Mode	TN
PPI	142
Viewing Angle	SVA 45/45/25/35

15.6" diagonal LED backlight FHD Slim DP SVA (1920 x 1080) Touch with Camera

Outline Dimensions (W x H x D)	360 x 224.3 (mm) max
Active Area	344.2 x 193.5 (mm)
Weight	430 g.
Diagonal Size	15.6"
Surface Treatment	Anti-smudge/fingerprint coating
Contrast Ratio	400:1 (typical)
Touch Enabled	Yes
TSP Type	Capacitive
Refresh Rate	60Hz
Brightness	300nits

Technical Specifications – Displays

15.6-inch UHD UWVA IPS LED anti-glare (3840 x 2160)	Pixel Resolution	Format	1920 x 1080 (FHD)
	Interface	Configuration	RGB Stripe
	LCD Mode	eDP 1.2	
	PPI	TN	
	Viewing Angle	142	
	Active Area (W x H)	SVA 45/45/25/35	
	Dimensions (W x H)	345.6 x 194.4 (mm)	
	Weight	15.6 in	
	Surface Treatment	560 g	
	Contrast Ratio	Anti-Glare (AG)	
	Refresh Rate	1000:1 (typical)	
	Brightness	60 Hz	
	Pixel Resolution	340 nits typical	1920 x 1080 (FHD)
	Backlight	Format	RGB
PPI	LED		
Viewing Angle	282		
	UWVA 85/85/85/85		

Technical Specifications – Storage

STORAGE AND DRIVES*

500 GB 5400rpm Self Encrypting Drive (FIPS-140-2) (Opal 2)

Drive Weight	0.21 lbs (95 g)
Capacity	500 GB
Height	0.28 in (7 mm)
Width	2.75 in (69.85 mm)
Interface	ATA-8, SATA 3.0
Transfer Rate	Synchronous (maximum) 600 MB/s
Seek Time (typical reads, including settling)	Single Track 1.5 ms
	Average 12ms
	Maximum 21ms
Cache	32MB
Rotational Speed	7200 rpm
Logical Blocks	976,773,168
Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
Features	ATA Security; TCG Opal 2.x, FIPS, S.M.A.R.T., NCQ, Ultra DMA

500 GB 7200rpm Hard Drive

Drive Weight	0.20 lbs (92 g)-0.21 lbs (95 g)
Capacity	500 GB
Height	0.28 in (7 mm)
Width	2.75 in (69.85 mm)
Interface	ATA-8, SATA 3.0
Transfer Rate	Synchronous (maximum) 600 MB/s
Seek Time (typical reads, including settling)	Single Track 1.5 ms ~ -2.0 ms
	Average 11 ms ~ -13 ms
	Maximum 18 ms ~ -22 ms
Cache	32MB
Rotational Speed	7200 rpm
Logical Blocks	976,773,168
Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
Features	ATA Security, S.M.A.R.T., NCQ, Ultra DMA

500 GB 7200rpm Self-Encrypting Drive (Opal 2)

Drive Weight	0.21 lbs (95 g)
Capacity	500 GB
Height	0.28 in (7 mm)
Width	2.75 in (69.85 mm)
Interface	ATA-8, SATA 3.0
Transfer Rate	Synchronous (maximum) 600 MB/s
Seek Time (typical reads, including settling)	Single Track 1.5ms
	Average 12ms
	Maximum 21ms
Cache	32MB
Rotational Speed	7200rpm
Logical Blocks	976,773,168
Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
Features	ATA Security; TCG Opal 2.x, S.M.A.R.T., NCQ, Ultra DMA

1 TB 5400rpm Hard Drive

Drive Weight	0.21 lbs (94 g)- 0.21 lbs (95 g)
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Technical Specifications – Storage

	Capacity	1 TB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	Synchronous (maximum) 600 MB/s		
	Seek Time	Single Track 2ms		
	(typical reads, including settling)	Average 12ms-13ms		
		Maximum 18ms-22ms		
	Cache	Up to 32MB		
	Rotational Speed	5400rpm		
	Logical Blocks	1,953,525,168		
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]		
	Features	ATA Security, S.M.A.R.T., NCQ, Ultra DMA		
500 GB Hybrid, 8 GB cache	Drive Weight	0.20 lbs (92 g) ~ 0.21 lbs (95 g)		
	Capacity	500 GB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	Synchronous (maximum) 600 MB/s		
	Seek Time	Single Track 2 ms		
	(typical reads, including settling)	Average 12 ms		
		Maximum 22 ms		
	Cache	64MB		
	Rotational Speed	5400 rpm		
	Logical Blocks	976,773,168		
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]		
Features	ATA Security, S.M.A.R.T., NCQ, Ultra DMAATA Security			
256 GB M2 2280 SATA-3 Self-Encrypting Drive (Opal 2) TLC Solid State Drive	Drive Weight	0.02 lb (10 g)		
	Capacity	256 GB		
	Height	0.09 in (2.23 mm)		
	Width	0.87 in (22 mm)		
	Interface	ATA-8, SATA 3.0		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		Up to 530 MB/s	UP to 515 MB/s	
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLP		
HP Z Turbo Drive 512 GB, M.2 NVMe MLC Solid State Drive	Drive Weight	0.022 lb (10 g)		
	Capacity	512 GB		
	Height	0.09 in (2.3 mm) ~ 0.14 in (3.65 mm)		
	Width	0.87 in (22 mm)		
	NAND Type	MLC		

Technical Specifications – Storage

Form-Factor (I/O)	M.2 2280	
Interface	PCIe NVMe Gen3X4	
Performance	Maximum Sequential Read	Maximum Sequential Write
	Up to 2288 MB/s	Up to 1600MB/s
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security (option), TRIM; L1.2	

HP Z Turbo Drive 1 TB, M.2 NVMe MLC Solid State Drive

Drive Weight	0.02 lb (10 g)	
Capacity	1024 GB	
Height	0.14 in (3.65 mm)	
Width	0.87 in (22 mm)	
NAND Type	MLC	
Form-Factor (I/O)	M.2 2280	
Interface	PCIe NVMe Gen3X4	
Drive Weight	0.02 lb (10 g)	
Performance	Maximum Sequential Read	Maximum Sequential Write
	Up to 2,400 MB/s	Up to 1,500 MB/s
Logical Blocks	2,000,409,264	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security, TRIM; L1.2	

HP Z Turbo Drive 256 GB, M.2 NVMe TLC Solid State Drive

Drive Weight	0.02 lb (10 g)	
Capacity	256 GB	
Height	0.09 in (2.23 mm)	
Width	0.87 in (22 mm)	
Generation	SM951 NVMe	
NAND Type	MLC	
Form-Factor (I/O)	M.2 2280	
Interface	PCIe NVMe Gen3X4	
Performance	Maximum Sequential Read	Maximum Sequential Write
	Up to 2,600 MB/s	Up to 900 MB/s
Logical Blocks	500,118,192	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security (Option); TRIM; L1.2	

HP Z Turbo Drive 512 GB, M.2 NVMe TLC Opal 2 Solid State Drive

Drive Weight	0.02 lb (10 g)
Capacity	512 GB
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)

Technical Specifications – Storage

Generation	TLC	
NAND Type	M.2 2280	
Form-Factor (I/O)	PCIe NVMe Gen3X4	
Interface	0.02 lb (10 g)	
Performance	Maximum Sequential Read	Maximum Sequential Write
	Up to 2,600 MB/s	Up to 1,400 MB/s
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security (Option);TRIM; L1.2	

*For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows® 7) of system and up to 30 GB (for Windows® 8) disk is reserved for system recovery software.

Technical Specifications – Security

SECURITY

HP Fingerprint Sensor	Voltage	3.0-3.6V
	Operating temperature	14° - 167°F (-10° - 75°C)
	Current consumption image	36mA
	Low latency wait for finger	950 uA
	Capture rate	3000 lines/sec
	ESD Resistance	IEC 6100-4-2 4B (+/-15KV)
	Detection Matrix	200*1 (plus another secondary line); 508 dpi, sensor area 12*3 mm

Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel® I219-LM Gigabit Network Connection (vPro configurations)

Ethernet Features

10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
 100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3. Clauses 40)
 Auto-Negotiation (Automatic Speed Selection)
 Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
 IEEE 802.1p QoS (Quality of Service) Support
 IEEE 802.1q VLAN support
 IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
 IEEE 802.3az EEE(Energy Efficient Ethernet)
 Jumbo Frame 9K
 Auto MDI/MDIX Crossover cable detection

Power Management Performance Features

ACPI compliant - multiple power modes
 Energy Detect Low Power Mode(Green Ethernet)
 TCP/IP/UDP Checksum Offload (configurable)
 Protocol Offload(ARP & NS)
 Large send offload and Giant send offload
 Receiving Side Scaling
 MACSec Offload (802.3ae)

Manageability

Intel® vPro
 iSCSI Boot
 RSS is kernel based support (e.g. in Win Server 2013)
 Ultra Low Power at cable disconnect (<1mW) enables platform support for connected standby.
 Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)
 PXE 2.1 Remote Boot
 Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
 Comprehensive diagnostic and configuration software suite
 Virtual Cable Doctor for Ethernet cable status

Interface

PCI Express 1.1 x1 to fully support ASPM L0s/L1 and CLKREQ.
NOTE: Intel® I219-LM Gigabit interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.

NIC Device Driver Name

Intel® Ethernet Network Connection I219-LM

Technical Specifications – Networking

Intel® I219-V Gigabit Network Connection (Non-vPro configurations)

Ethernet Features

10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
100 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 Clauses 40)
Auto-Negotiation (Automatic Speed Selection)
Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE 802.1p QoS (Quality of Service) Support
IEEE 802.1q VLAN support
IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
IEEE 802.3az EEE(Energy Efficient Ethernet)
Jumbo Frame 9K
Auto MDI/MDIX Crossover cable detection

Power Management

ACPI compliant - multiple power modes
Energy Detect Low Power Mode(Green Ethernet)

Performance Features

TCP/IP/UDP Checksum Offload (configurable)
Protocol Offload(ARP & NS)
Large send offload and Giant send offload
Receiving Side Scaling
MACSec Offload (802.3ae)
Intel Non-vPro
iSCSI Boot

Manageability

Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)
PXE 2.1 Remote Boot
Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
Comprehensive diagnostic and configuration software suite
Virtual Cable Doctor for Ethernet cable status

Interface

PCI Express 1.1 x1 to fully support ASPM L0s/L1 and CLKREQ.
NOTE: Intel 82579 PCIe interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.

NIC Device Driver Name

Intel 82579LM/82579V Ethernet Network Connection

Technical Specifications – Networking

HP lt4132 Qualcomm® Snapdragon™ X5 LTE Mobile Broadband Module*	Technology/Operating Bands	LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 800 (Band 20), 700 (Band 28). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz EV-DO: 850 (BC0), 1900 (BC1) MHz (Only work with Verizon network) E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz
	Wireless Protocol Standards	3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification 1xEVDO Release 0, A and B. E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4 and MSC1 - MSC9
	GPS	Standalone, A-GPS (MS-A, MS-B and XTRA)
	GPS Bands	1575.42 MHz (± 1.023 MHz), GLONASS 1596-1607MHz
	Maximum Data Rates	LTE: 150 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) CDMA 1xRTT: 153.6 kbps (Download), 153.6 kbps (Upload) EVDO Rel.A: 3.1 Mbps (Download), 1.8 Mbps (Upload) EVDO Rel.B: 14.7 Mbps (Download), 5.4Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
	Maximum Output Power	LTE: 23 dBm HSPA+: 23.5 dBm 1xRTT/EVDO: 24dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
	Maximum Power Consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) 1xRTT/EVDO: 1,000 mA (peak); 700 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	6.2 g
	Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications – Networking

HP hs3210 HSPA+ Intel® Mobile Broadband Module*	<p>Technology/Operating Bands LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 800 MHz (Band 20, DD800) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz</p> <p>Wireless Protocol Standards WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9</p> <p>GPS Standalone, A-GPS</p> <p>GPS Bands 1575.42 MHz (± 1.023 MHz)</p> <p>Maximum Data Rates HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) E-GPRS: 296 kbps (Download), 236.8 kbps (Upload) GPRS: 107 kbps (Download), 85.6 kbps (Upload)</p> <p>Maximum Output Power HSPA+: 24 dBm E-GPRS 1800/1900: 26 dBm E-GPRS 850/900: 27 dBm GPRS 1800/1900: 30 dBm GPRS 850/900: 33 dBm</p> <p>Maximum Power Consumption HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 700 mA (average)</p> <p>Form Factor M.2, 3042-S3 Key B</p> <p>Weight 6 g</p> <p>Dimensions (Length x Width x Thickness) 1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)</p> <p><small>*Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.</small></p>
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HP lt4120 Qualcomm® Snapdragon™ X5 LTE Mobile Broadband Module*	<p>Technology/Operating Bands LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 800 (Band 20), 700 (Band 28). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz EV-DO: 850 (BC0), 1900 (BC1) MHz (Only work with Verizon network) E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz</p> <p>Wireless Protocol Standards 3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification 1xEVDO Release 0, A and B. E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4 and MSC1 - MSC9</p> <p>GPS Standalone, A-GPS (MS-A, MS-B and XTRA)</p> <p>GPS Bands 1575.42 MHz (± 1.023 MHz), GLONASS 1596-1607MHz</p> <p>Maximum Data Rates LTE: 150 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload)</p>
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Technical Specifications – Networking

	HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) CDMA 1xRTT: 153.6 kbps (Download), 153.6 kbps (Upload) EVDO Rel.A: 3.1 Mbps (Download), 1.8 Mbps (Upload) EVDO Rel.B: 14.7 Mbps (Download), 5.4Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
Maximum Output Power	LTE: 23 dBm HSPA+: 23.5 dBm 1xRTT/EVDO: 24dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
Maximum Power Consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) 1xRTT/EVDO: 1,000 mA (peak); 700 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6.2 g
Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications – Networking

<p>Intel® Dual Band Wireless-AC 8265 802.11 AC/a/b/g/n (2x2) WiFi + Bluetooth® 4.2 Combo Adaptor* (vPro)</p>	<p>Wireless LAN Standards</p>	<p>IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11n</p>
	<p>Interoperability</p>	<p>Wi-Fi certified</p>
	<p>Frequency Band</p>	<p>802.11b/g/n 2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels</p> <p>802.11a 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)</p>
	<p>Data Rates</p>	<ul style="list-style-type: none"> • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	<p>Modulation</p>	<p>Direct Sequence Spread Spectrum CCK, BPSK, QPSK, 16-QAM, 64-QAM, 256-QAM</p>
	<p>Security¹</p>	<ul style="list-style-type: none"> • IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI
	<p>Network Architecture Models</p>	<p>Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)</p>
	<p>Roaming</p>	<p>IEEE 802.11 compliant roaming between band Access Points</p>
	<p>Output Power²</p>	<ul style="list-style-type: none"> • 802.11b : +16dBm minimum • 802.11g : +14dBm minimum • 802.11a : +14dBm minimum • 802.11n HT20(2.4GHz) : +13dBm minimum • 802.11n HT40(2.4GHz) : +13dBm minimum • 802.11n HT20(5GHz) : +12dBm minimum • 802.11n HT40(5GHz) : +12dBm minimum
	<p>Power Consumption</p>	<p>Transmit: 2.0 Watts (max) Receive: 1.6 Watts (max)</p>

Technical Specifications – Networking

	Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10mW (WLAN + BT) Radio disabled: 5 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	802.11b, 1Mbps : -94dBm maximum 802.11b, 11Mbps : -86dBm maximum 802.11g, 6Mbps : -88dBm maximum 802.11g, 54Mbps : -74dBm maximum 802.11a, 6Mbps : -88dBm maximum 802.11a, 54Mbps : -74dBm maximum 802.11n, MCS07 : -69dBm maximum 802.11n, MCS15 : -66dBm maximum 802.11ac, 1SS, MCS-0 : -86dBm maximum 802.11ac, 1SS, MCS-9 : -61dBm maximum 802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm Or Type 1630 : 2.3 x 16.0 x 30.0 mm
Weight	Type 2230 : 2.8g Or Type 1630 : 2g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating Non-operating 0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON

Technical Specifications – Networking

HP Integrated Module with Bluetooth® 4.2 Wireless Technology	Bluetooth® Specification	4.2 Compliant												
	Frequency Band	2402 to 2480 MHz												
	Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)												
	Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)												
	Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of +4 dBm for BR and EDR												
	Receiver Sensitivity	<table border="1"> <thead> <tr> <th>Modulation</th> <th>0.01% BER</th> <th>0.001% BER</th> </tr> </thead> <tbody> <tr> <td>GFSK</td> <td>-80 dBm</td> <td>-70 dBm</td> </tr> <tr> <td>$\pi/4$-DQPSK</td> <td>-80 dBm</td> <td>-70 dBm</td> </tr> <tr> <td>8DPSK</td> <td>-80 dBm</td> <td>-70 dBm</td> </tr> </tbody> </table>	Modulation	0.01% BER	0.001% BER	GFSK	-80 dBm	-70 dBm	$\pi/4$ -DQPSK	-80 dBm	-70 dBm	8DPSK	-80 dBm	-70 dBm
Modulation	0.01% BER	0.001% BER												
GFSK	-80 dBm	-70 dBm												
$\pi/4$ -DQPSK	-80 dBm	-70 dBm												
8DPSK	-80 dBm	-70 dBm												
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW												
	Antenna	Internally integrated within module												
	Range	Legacy Up to 33 ft (10 m) BLE Up to 99 ft (30 m)												
	Electrical Interface	USB 2.0 compliant												
	Bluetooth® Software Supported	Microsoft Windows Bluetooth Software												
	Link Topology	Point to Point, Multipoint Pico Nets up to 7 slaves												
	Security	Full support of Bluetooth Security Provisions												
	Power Management	Microsoft Windows ACPI, and USB Bus Support												
	Certifications	Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff												
	Security	All necessary regulatory approvals for supported countries, including: FCC (47 CFR) Part 15C, Section 15.247 & 15.249												
	Power management certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark												
	Certifications	Serial Port Profile (SPP)1												
	Bluetooth® Profiles Supported	Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN)1,2 Generic Object Exchange Profile (GOEP)1,2 Object Push Profile (OPP)1,2 Hard Copy Cable Replacement (HCRP)1,2 Personal Area Networking Profile (PAN)1,2 Human Interface Device Profile (HID)1,2 Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Audio Video Remote Control Profile (AVRCP)												

Technical Specifications – Networking

Bluetooth® V4.2 support feature

V4.2: ESR8 compliant, LE Secure Connection – Basic.

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CCK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

WLAN supplier's client utility is required for Cisco Compatible Extensions support with Microsoft Windows XP. WLAN may also be compatible with certain third-party software supplicants. WLAN supplier IHV extensions required for Cisco Compatible Extensions support for Microsoft Windows Vista.

Technical Specifications – Networking

**Intel® Dual Band
Wireless-AC 8265 802.11
AC/a/b/g/n (2x2) WiFi +
Bluetooth® 4.2 Combo
Adaptor* (non-vPro)**

Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac

**Interoperability
Frequency Band**

Wi-Fi certified
802.11b/g/n

2.402 - 2.482 GHz

Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels

802.11a

- 4.9 - 4.95 GHz (Japan)
- 5.15 - 5.25 GHz
- 5.25 - 5.35 GHz
- 5.47 - 5.725 GHz
- 5.825 - 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)

Antenna Structure

2 transmit; 2 receive (2x2)

Data Rates

802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: card will support rates for NSS=1 and NSS=2 for RX and TX for 20 and 40 MHz channels. Short and long guard interval shall be supported.

802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security¹

- IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI

**Network Architecture
Models**

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power²

- 802.11b : +16dBm minimum
- 802.11g : +14dBm minimum
- 802.11a : +14dBm minimum

Technical Specifications – Networking

- 802.11n HT20(2.4GHz) : +13dBm minimum
- 802.11n HT40(2.4GHz) : +13dBm minimum
- 802.11n HT20(5GHz) : +12dBm minimum
- 802.11n HT40(5GHz) : +12dBm minimum
- 802.11ac 80MHz(5GHz) : +11dBm minimum

Power Consumption	Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 60 mW (WLAN unassociated) Radio disabled: 30 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	802.11g:-90 dBm (6 Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), -85 dBm (18 Mbps), -82 dBm (24 Mbps), -79 dBm (36 Mbps), -76 dBm (48 Mbps), -74 dBm (54 Mbps) 802.11b:-95 dBm (1 Mbps), -93 dBm (2 Mbps), -91 dBm (5.5 Mbps), -88 dBm (11 Mbps) 802.11g:-90 dBm (6 Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), -85 dBm (18 Mbps), -82 dBm (24 Mbps), -79 dBm (36 Mbps), -76 dBm (48 Mbps), -74 dBm (54 Mbps) 802.11n:-69 dBm (150 Mbps), -66 dBm (300 Mbps)
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express Half-MiniCard
Dimensions	0.134 x 1.06 x 1.18 in (3.4 x 26.8 x 30 mm)
Weight	3.1g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft. (3,048 m) Non-operating 0 to 50,000 ft. (15,240 m)
LED Activity	LED Amber - Radio OFF; LED White - Radio ON

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth® 4.2 Wireless Technology

Bluetooth Specification	4.0+EDR Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	79 (1 MHz) available channels
Data Rates and Throughput	3 Mbps data rate; throughput up to 2.17 Mbps

Technical Specifications – Networking

	Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric or 1306.9 kbps symmetric
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of +4 dBm for BR and EDR
Receiver Sensitivity	Better than -20 dBm at 0.1 % raw bit error rate
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Antenna	Internally integrated within module
Range	Up to 33 ft. (10 m)
Electrical Interface	USB 2.0 compliant Microsoft Windows Plug and Play compliant
Bluetooth® Software Supported	Broadcom Bluetooth for Windows Microsoft Windows Bluetooth Software
Link Topology	Point to Point, Multipoint Pico Nets up to 7 slaves
Security	Full support of Bluetooth Security Provisions
Power Management	Microsoft Windows ACPI, and USB Bus Support Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff
Certifications	All necessary regulatory approvals for supported countries, including: FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth® Profiles Supported	Serial Port Profile (SPP) ¹ Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN) ^{1,2} Generic Object Exchange Profile (GOEP) ^{1,2} Object Push Profile (OPP) ^{1,2} File Transfer Profile (FTP) Synchronization Profile (SYNC) Hard Copy Cable Replacement (HCRP) ^{1,2} Personal Area Networking Profile (PAN) ^{1,2} Human Interface Device Profile (HID) ^{1,2} FAX Profile (FAX) Basic Imaging Profile (BIP) ² Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Indicates the profile is supported by Microsoft Windows XP SP2

2. Indicates the profile is part of Windows Vista

* Wireless access point and internet service required. Availability of public wireless access points limited.

Technical Specifications – Networking

<p>Intel® Dual Band Wireless-AC 3168 802.11 ac (1x1) WiFi and Bluetooth® 4.2 Combo Adapter (non-vPro)</p>	<p>Wireless LAN Standards</p>	<p>IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac</p>
	<p>Interoperability</p>	<p>Wi-Fi certified</p>
	<p>Frequency Band</p>	<p>802.11b/g/n</p> <ul style="list-style-type: none"> • 2.402 – 2.482 GHz
		<p>Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.</p>
		<p>802.11a/n</p> <ul style="list-style-type: none"> • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	<p>Data Rates</p>	<p>Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)</p> <ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS7, (1SS) (20MHz, 40MHz, and 80MHz)
	<p>Modulation</p>	<p>Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM</p>
	<p>Security¹</p>	<ul style="list-style-type: none"> • IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI
	<p>Network Architecture Models</p>	<p>Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)</p>
	<p>Roaming</p>	<p>IEEE 802.11 compliant roaming between access points</p>
	<p>Output Power²</p>	<ul style="list-style-type: none"> • 802.11b : +16dBm minimum • 802.11g : +14dBm minimum • 802.11a : +14dBm minimum • 802.11n HT20(2.4GHz) : +13dBm minimum • 802.11n HT40(2.4GHz) : +13dBm minimum • 802.11n HT20(5GHz) : +12dBm minimum • 802.11n HT40(5GHz) : +12dBm minimum • 802.11ac 80MHz(5GHz) : +11dBm minimum
	<p>Power Consumption</p>	<p>Transmit: 2.0 W (max)</p>

Technical Specifications – Networking

	Receive: 1.6 W (max)
	Idle mode (PSP): 180 mW (WLAN Associated)
	Idle mode: 60 mW (WLAN unassociated)
	Radio disabled: 30 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	802.11b, 1Mbps : -94dBm maximum 802.11b, 11Mbps : -86dBm maximum 802.11g, 6Mbps : -88dBm maximum 802.11g, 54Mbps : -74dBm maximum 802.11a, 6Mbps : -86dBm maximum 802.11a, 54Mbps : -72dBm maximum 802.11n, MCS07 : -69dBm maximum 802.11n, MCS15 : -66dBm maximum 802.11ac, 1SS, MCS-0 : -86dBm maximum 802.11ac, 1SS, MCS-9 : -61dBm maximum 802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm Or Type 1630 : 2.3 x 16.0 x 30.0 mm
Weight	Type 2230 : 2.8g Or Type 1630 : 2g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating 40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)
Near Field Communications (NFC)	
Controller	HP Module with NXP NFC Controller NPC100
Supports	<ul style="list-style-type: none"> • Windows 8, Proximity Events • Windows 7, PC/SC • NFC Forum Compliant • Near Field Communications Controller
Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm
Chipset	NPC100
System interface	I2C
NFC RF standards	standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2

Technical Specifications – Networking

NFC Forum Support Tag	Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
Reader	(PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards
Card Emulation	(PICC-VICC)
Mode¹	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
Frequency	13.56 MHz
NFC Modes Supported	Reader/Writer, Peer-to-Peer
Raw RF Data Rates	106, 212, 424, 848 kbps
Operating temperature	0°C to 70°C
Storage temperature	-20°C to 125°C
Humidity	10-90% operating 5-95% non-operating
Supply Operating voltage	2.97 to 5.5 Volts
I/O Voltage	1.8V or 3.3V
Power Consumption	Booster enable, VBAT= 3.3V, VCC_BOOST = 5V) Typical ² Polling 7.3 mA Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA Detected Test Tag Type 4 Total 282.3 mA Net Module 235.3 mA Mode Power Consumption,
Antenna connector	0.5mm pitch, 7 connector FPC. Antenna matching is external to module.
Notes	<ol style="list-style-type: none">1. With application or UICC support2. Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured.

Technical Specifications – Audio

AUDIO/MULTIMEDIA – BANG & OLUFSEN

Hardware	Implementation	Conexant CX7700
	Function Key	Volume up, volume down, and mute
	Volume Controls	
	Full Duplex	Yes
	Microphone In	Stereo
	Headphone/Line Out	Stereo
	Integrated Microphone	Yes, dual digital microphone array when equipped with optional webcam

Audio Output Quality	Frequency Response	20 Hz - 20 kHz
	Signal to Noise Ratio	106dB (DAC), 102dB (ADC)
	Total Harmonic Distortion	91dB THD+n on LineOut/HP (0.003%)
	Noise Floor	-110 dB
	Play Sampling Rate(s)	Up to 192kHz
	Record Sampling Rate(s)	Up to 96kHz
	DAC	16, 20 or 24-bit
	ADC	16,20 or 24-bit

Integrated Stereo Speakers	Power Rating	2 Watts
	Impedance	4 Ohms

Technical Specifications – Power

POWER

HP 65W Smart AC Adapter	Dimensions	107.0x47.0x30.0mm	
	Weight	unit: 250g +/- 10g	
	Input	90 to 265 VAC	
		Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
		Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	AC Connector (Ac Inlet)	C6 (3pin/with grounded, with Smart ID DC connector)	
	AC Connector (Ac Inlet) Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
	Storage Humidity	10% to 95%	
EMI and Safety Certifications	*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.		

HP 65W Smart AC Adapter EM	Dimensions	102.0x55.0x30.0mm	
	Weight	unit: 350g +/- 10g	
	Input	90 to 265 VAC	
		Input Efficiency	87.0% min at 115 VAC and 230Vac
		Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 VAC
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
AC Connector (Ac Inlet)	C6 (3pin/with grounded, with Smart ID DC connector)		

Technical Specifications – Power

AC Connector (Ac Inlet) Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5,000 m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	<p>*CE Mark - full compliance with LVD and EMC directives</p> <p>* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.</p> <p>* MTBF - over 200,000 hours at 25°C ambient condition.</p>	

HP 65W Travel AC Adapter	Dimensions	120.0x57.6x16.7mm	
	Weight	unit: 250g +/- 10g	
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
		Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V/5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	DC Plug	4.5mm/7.4mm tips	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
EMI and Safety Certifications	<p>*CE Mark - full compliance with LVD and EMC directives</p> <p>* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.</p> <p>* MTBF - over 200,000 hours at 25°C ambient condition.</p>		

HP Long Life 3-cell Polymer Battery (51Whr)	Dimensions (H x W x L)	6.8mm x 102.8mm x 198mm	
	Weight	235 g	
	Cells/Type	3cell Lithium-Ion Polymer cell / 506480	
	Energy	Voltage	11.55V
		Amp-hour capacity	4420mAh
		Watt-hour capacity	51wh
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)
Operating (Discharging)		14° to 140° F(-10° to 60° C)	

Technical Specifications – Power

Fuel Gauge LED	No
Warranty	1000 cycles > 65% (at 23 °C)
Optional Travel Battery Available	No

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT <Gold> registered in the United States. See <http://www.epeat.net> for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.

Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	5.86 W	5.86 W	5.99 W
Normal Operation (Long idle)	3.14 W	3.73 W	3.40 W
Sleep	0.71 W	0.79 W	0.72 W
Off	0.40 W	0.48 W	0.40 W

Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	20 BTU/hr	20 BTU/hr	20 BTU/hr
Normal Operation (Long idle)	11 BTU/hr	13 BTU/hr	12 BTU/hr
Sleep	2 BTU/hr	3 BTU/hr	2 BTU/hr
Off	1 BTU/hr	2 BTU/hr	1 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.9	22
Fixed Disk – Random writes	3.5	28

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

Technical Specifications – Power

- 2 USB ports
- 1 Smart Card reader
- 1 SD Card reader
- 1 SIM module slot
- 2 SODIMM memory slots
- Optional expansion base docking station

Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater than 1ppm by weight
- Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the <Gold> level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 0% post-consumer recycled plastic (by wt.)
- This product is 95.2% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	348 g
Internal:	PLASTIC/Polyethylene Expanded - EPE	38 g
	PLASTIC/Polyethylene low density - LDPE	15 g
	PLASTIC/Polypropylene - PP	5 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 70% recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf>):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates

Technical Specifications – Power

- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP Inc. web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

Technical Specifications – Power

Country of Origin

China

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part #
Memory	HP 4GB DDR4-2400 SODIMM (Core processors only)	Z4Y84AA
	HP 16GB DDR4-2400 SODIMM (Core processors only)	Z4Y86AA
Cases	HP Executive 15.6 Black Top Load	P6N18AA
	HP Business Case (up to 15.6")	H5M92AA
Docking	HP UltraSlim Docking Station	D9Y32AA
	HP 2013 UltraSlim Docking Station TAA (US only)	E5C22AV#ABA
	HP Executive Travel Hub	TOK29AA
	HP Travel Hub	TOK30AA
	HP 3005pr USB 3.0 Port Replicator w/ USB-C Adapter	Y4H06AA
	HP Display and Notebook Stand II	E8G00AA#xxx
	HP USB-Type C™ Elite Dock	X7W54AA
Input/Output - Mice	HP Comfort Grip Mouse	H2L63AA
	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP Ultrathin Wireless Mouse	L9V78AA
	HP USB Travel Mouse	G1K28AA#xxx
	HP Slim Wireless Keyboard and Mouse	T6L04AA#xxx
	HP USB Essential Keyboard and Mouse	H6L29AA#xxx
	HP Slim USB Keyboard and Mouse	T6T83AA
HP Wireless (Link-5) Keyboard	T6U20AA#xxx	
Power Adapters	HP 65W Slim A/C Adapter w/USB	H6Y82AA
	HP 90W Slim A/C Adapter w/USB	H6Y83AA
	HP 90W Slim Auto Combo AC Adapter w/USB	H6Y84AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 90W Smart AC Adapter	H6Y90AA
Battery	HP TA03XL Rechargeable Battery	1FN06AA
Adapters	HP USB-C™ to VGA Adapter	N9K76AA
	HP USB-C to USB 3.0	N2Z63AA
	HP USB-C to USB Hub	Z6A00AA
	HP USB-C™ to DisplayPort™ Adapter	N9K78AA
	HP USB-C™ to DisplayPort™ Adapter	N9K78AA
	HP HDMI to DVI adapter	F5A28AA

Options and Accessories (sold separately and availability may vary by country)

	DisplayPort™ to DVI Adapter	F7W96AA
	DisplayPort™ to VGA	F7W97AA
	DisplayPort™ to HDMI 1.4 Adapter	F3W43AA
Wireless	HP Lt4120 LTE/EVDO/HSPA+ Gobi™ 4G Mobile Broadband Module	TBD
Collaboration	HP UC Conferencing Keyboard	K8P74AA#xxx
	HP UC Speaker Phone	K7V16AA
	HP UC Wired Headset	K7V17AA
	HP UC Mono Wireless Headset	W3K08AA
	HP UC Duo Wireless Headset	W3K09AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
Storage - External Storage	HP External USB DVDRW Drive	F2B56AA
	HP 500GB 7200rpm HDD	F3B97AA
	HP 256GB M2 NVME PCIe SSD (2280)	V3K66AA
	HP 512GB M2 NVME PCIe SSD (2280)	V3K67AA
Security	HP Dual Head Cable Lock (Non-Master key)	T1A64AA
	HP Dual Head Cable Lock (Master Key)	T1A65AA
	HP 15.6" Notebook PC Privacy Filter (non-touch)	J7H71AA
	HP Docking Station Cable Lock	AU656AA#XXX
	HP Essential Combination Lock	TOY16AA
	HP Combination Lock	TOY15AA
	HP Keyed Cable Lock	TOY14AA
	HP 15'6 Privacy Filter (touch panel)	V8Z58AA#xxx

NOTE: External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Summary of Changes

Date of change:	Version History:		Description of change:
March 1, 2017	From v1 to v2	Added	Intel 4120 and 4132 wireless networking cards,
		Changed	Phrasing of 3 bullet in at a Glance, Environmental section
April 1, 2017	From v2 to v3	Changed	Displays HDAG-touch and FHD weight
April 21, 2017	From v3 to v4	Changed	In the Power section under Battery Life subsection changed the results of the Battery life tests from 10 hours to 12 hours 14 min, Changed the EPEAT disclaimer to satisfy the criteria for a renewable energy accessory.
April 24, 2017	From v4 to v5	Removed	Integrated Bluetooth compatibility with 4.0, 4.1
August 1, 2017	From v5 to v6	Changed	From HP 8GB DDR4-2400 SODIMM to HP 16GB DDR4-2400 SODIMM as an Option Memory under the Options and Accessories section

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